

# Flicker Noise in Advanced CMOS Technology: Effects of Halo Implant

**Navid Paydavosi,**  
Sriramkumar Venugopalan,  
Angada Sachid,  
Ali Niknejad,  
Chenming Hu

Electrical Engineering and Computer Science  
University of California, Berkeley  
Berkeley, CA, U.S.A.



Sagnik Dey,  
Samuel Martin,  
Xin Zhang

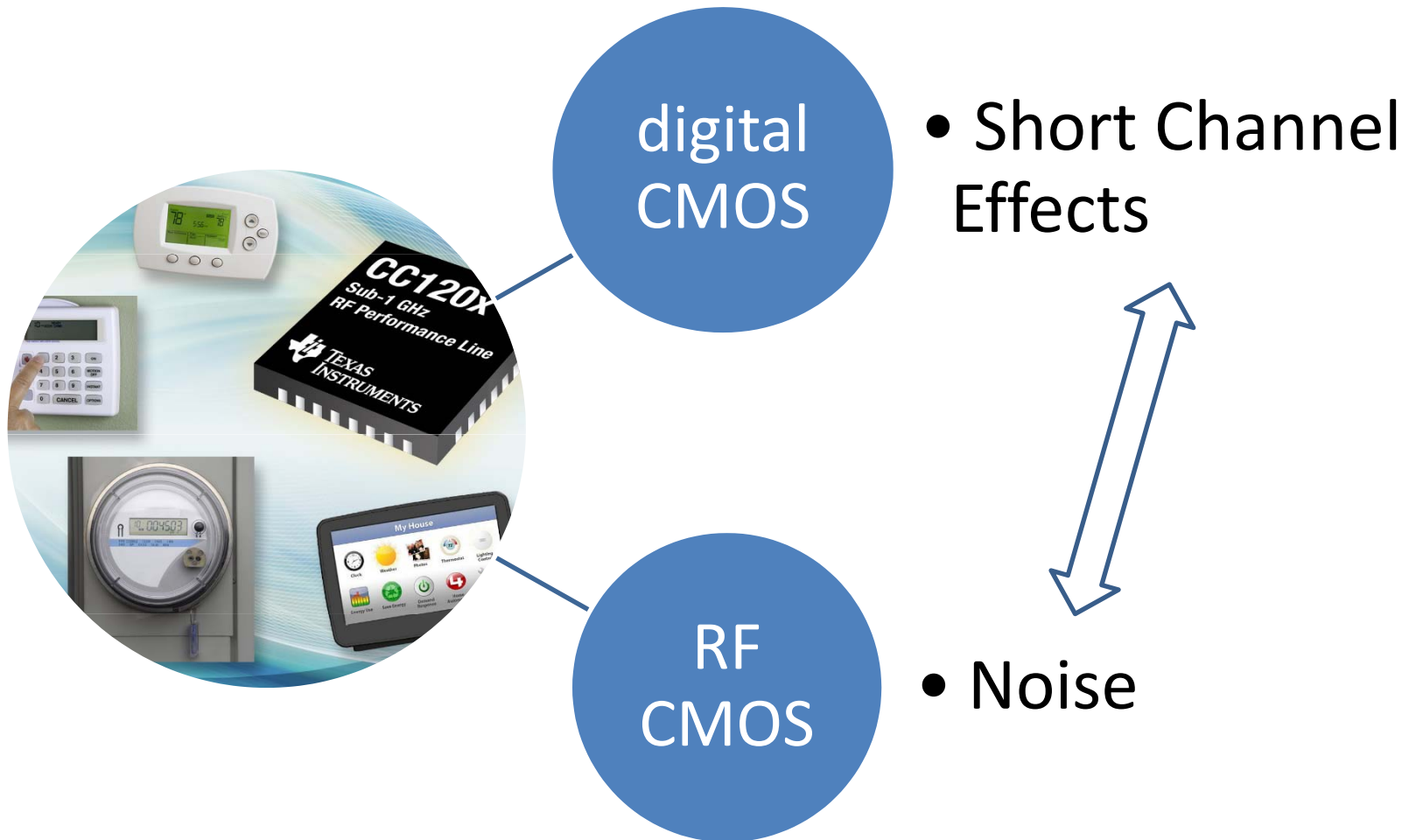
Advanced CMOS Technology Development  
Texas Instruments  
Dallas, TX, U.S.A



# Outline

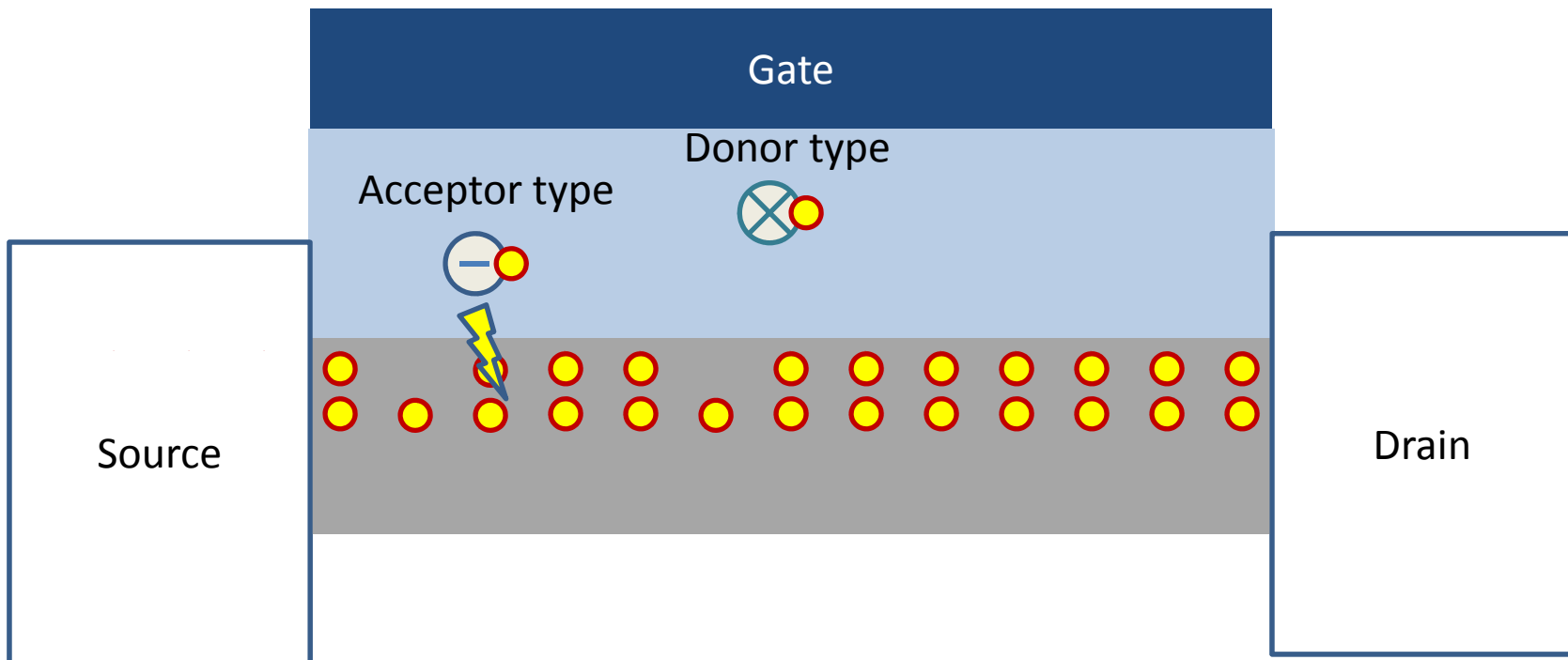
- Motivation
- Flicker Noise and Unified Flicker Noise Model
- Measurements
- Model
- Verification
- Discussions
- Conclusions

# Motivation: System On Chip



# Flicker ( $1/f$ ) Noise

- Flicker noise: the fluctuation of drain current due to Oxide Traps:
  1. Reduction in channel carrier density
  2. Change in mobility due to Coulomb Scattering



# Unified Flicker Noise Model

- The unified drain-current FN power density as a function of frequency  $f$

$$S_{ID}(f) = \frac{k_B T I_d^2}{\gamma f W L^2} \int_0^L \frac{N_t^*(E_{fn})}{N(x)^2} dx$$

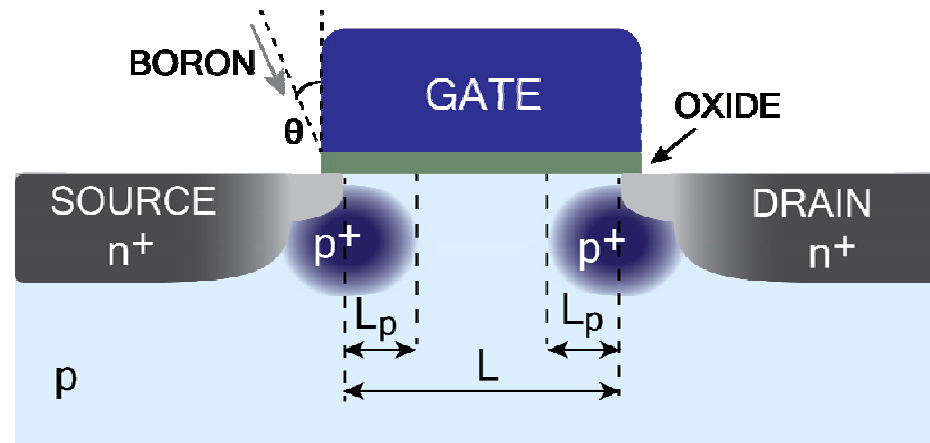
where  $N_t^*$  is the so-called **apparent trap density** given by  $N_t(E_{fn})(1 \pm \alpha \mu N)^2$

$N_t^*$  is approximated by the following function of  $N$ :

$$N_t^*(E_{fn}) = A + BN + CN^2$$

# Halo (Pocket) Implant

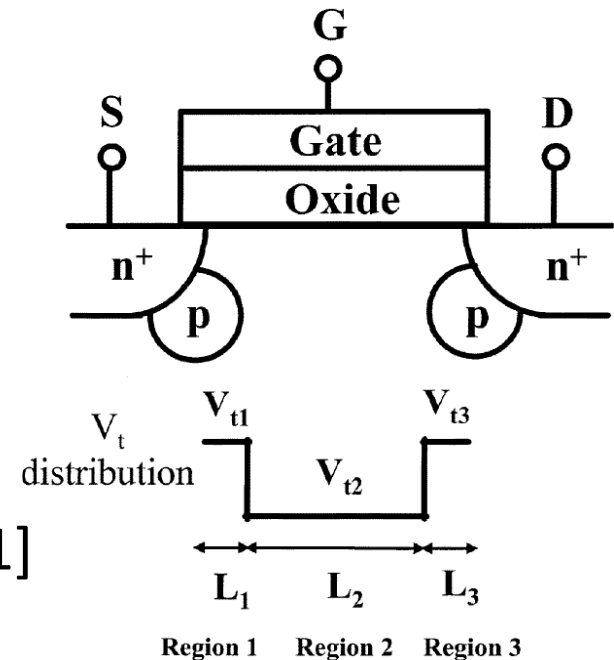
- non-uniform doping concentration



# Approaches Suggested in Literature

Assuming only non-uniform doping concentration:

$$\begin{aligned} \frac{S_{id}}{I_d^2} &= \frac{kT}{\gamma f W L_{eff}^2} N_t(E_{fn}) \\ &\times \left[ \int_{L_1} \frac{1}{N_1^2(x)} dx + \int_{L_2} \frac{1}{N_2^2(x)} dx + \int_{L_3} \frac{1}{N_3^2(x)} dx \right] \\ &\approx \frac{kT q^2}{\gamma f W L_{eff}^2 C_{ox}^2} N_t(E_{fn}) \\ &\times \left[ \frac{L_1}{(V_g - V_{t1})^2} + \frac{L_2}{(V_g - V_{t2})^2} + \frac{L_3}{(V_g - V_{t3})^2} \right] \quad [11] \end{aligned}$$

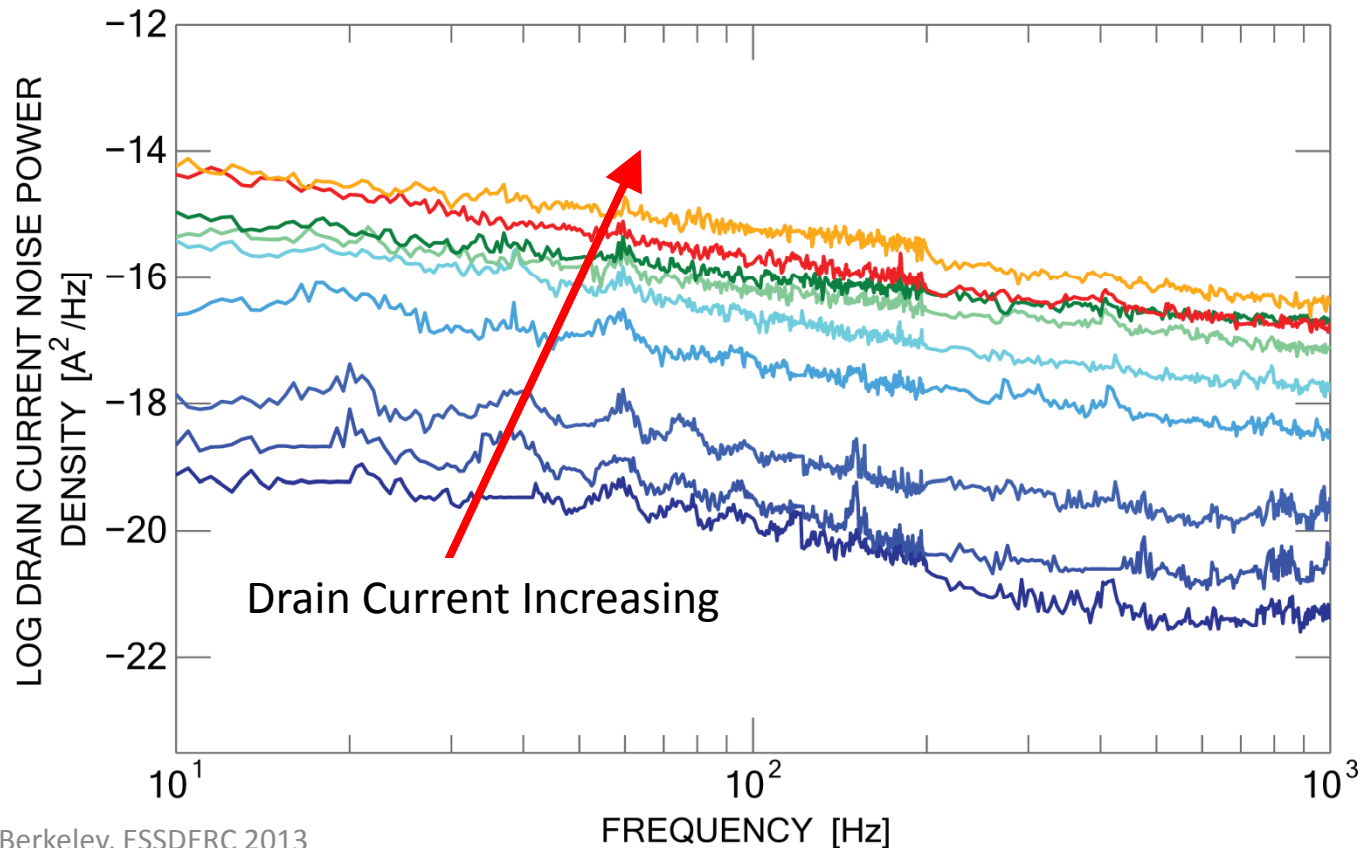


The equation and the graph have been taken directly from [11]:

Pocket implantation effect on drain current flicker noise in analog nMOSFET devices, Wu *et al.*, TED, vol. 51, no. 8, 2004

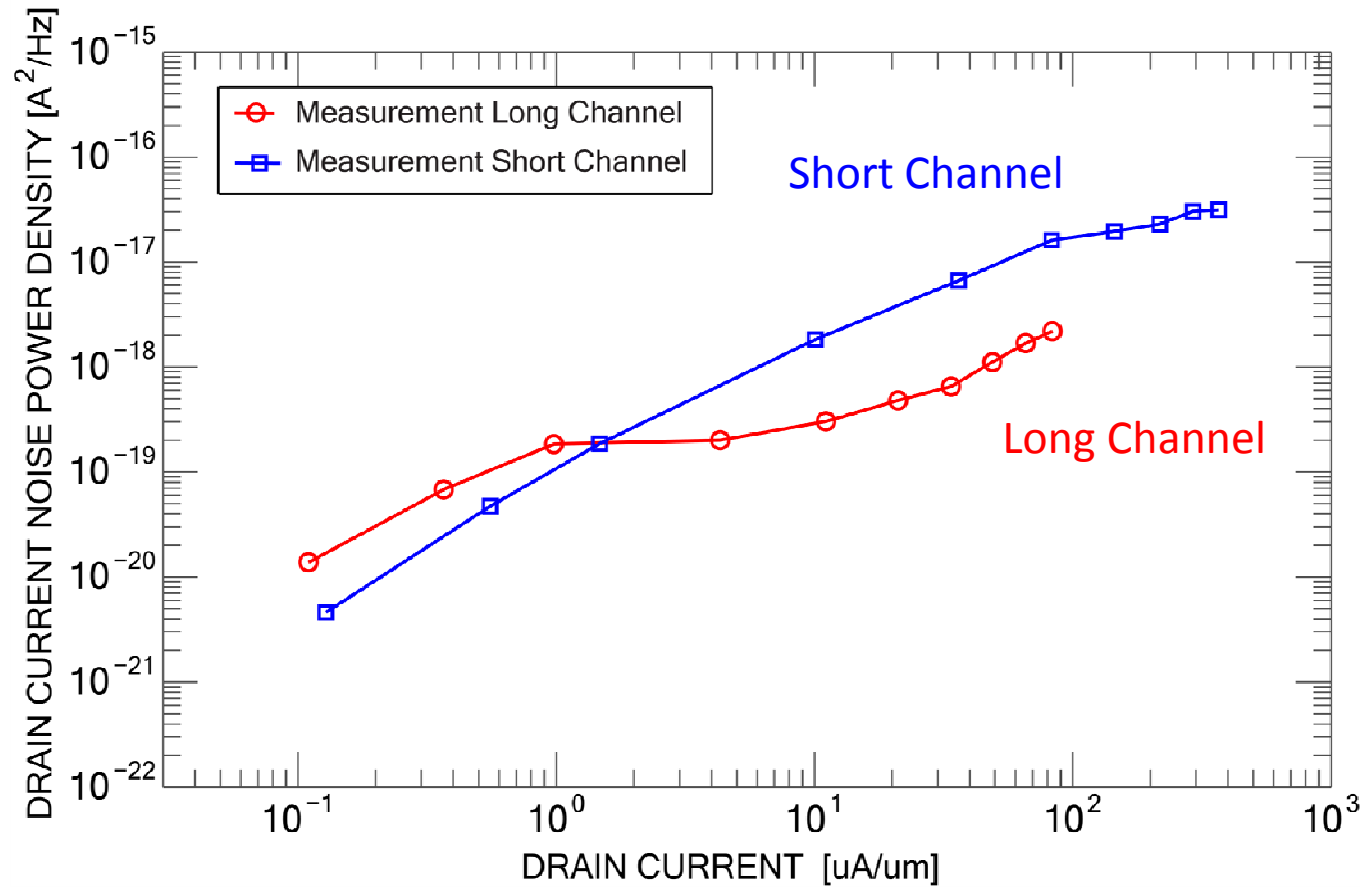
# Measurement

- Measurements were done on short and long-channel NMOSs fabricated by CMOS 45-nm node technology
- A **S300 semi-auto prober** with **BTA9812 noise analyzer** were used



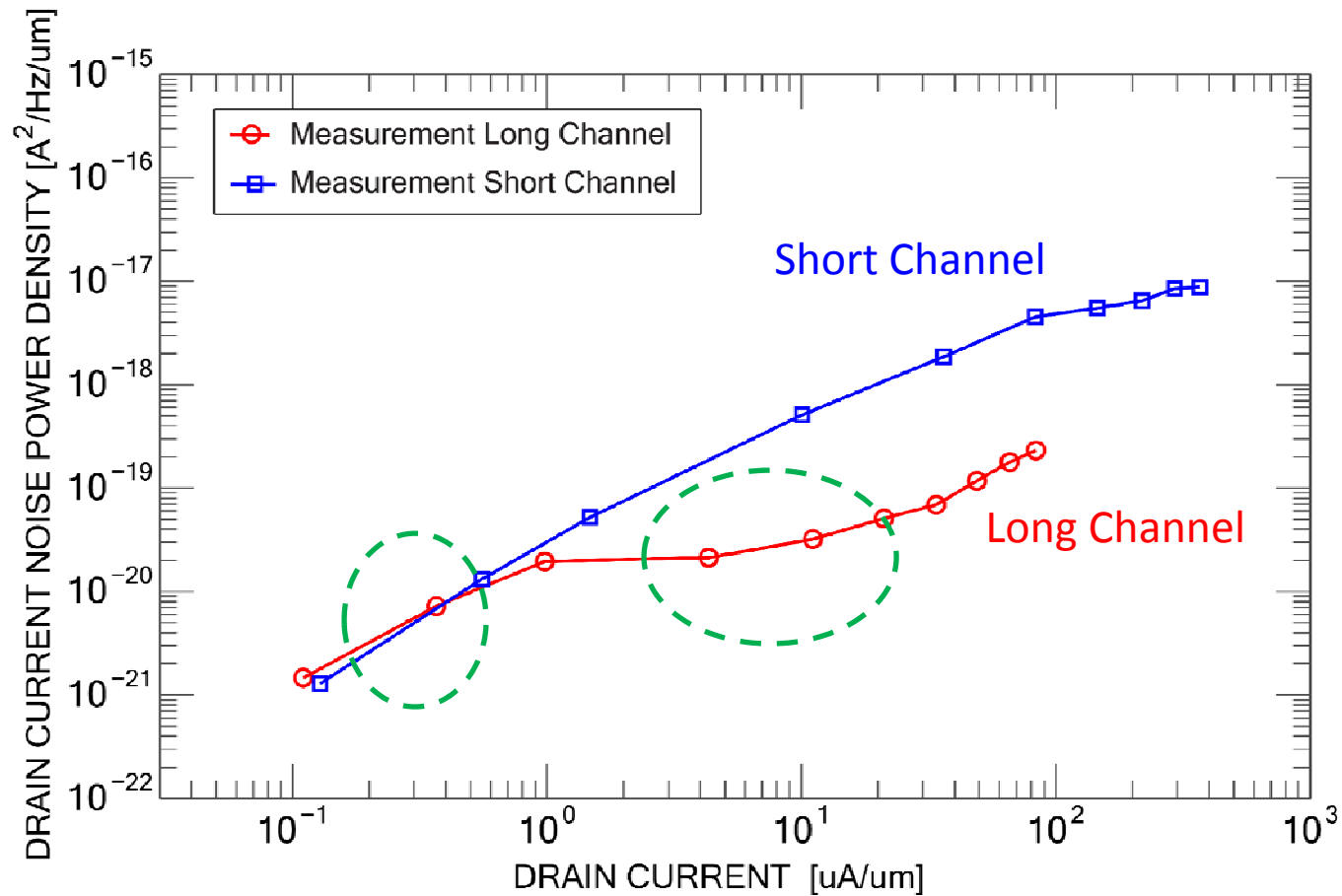


# Measurement



**Width:**  
**Long-channel: 10  $\mu m$**   
**Short-channel: 5  $\mu m$**

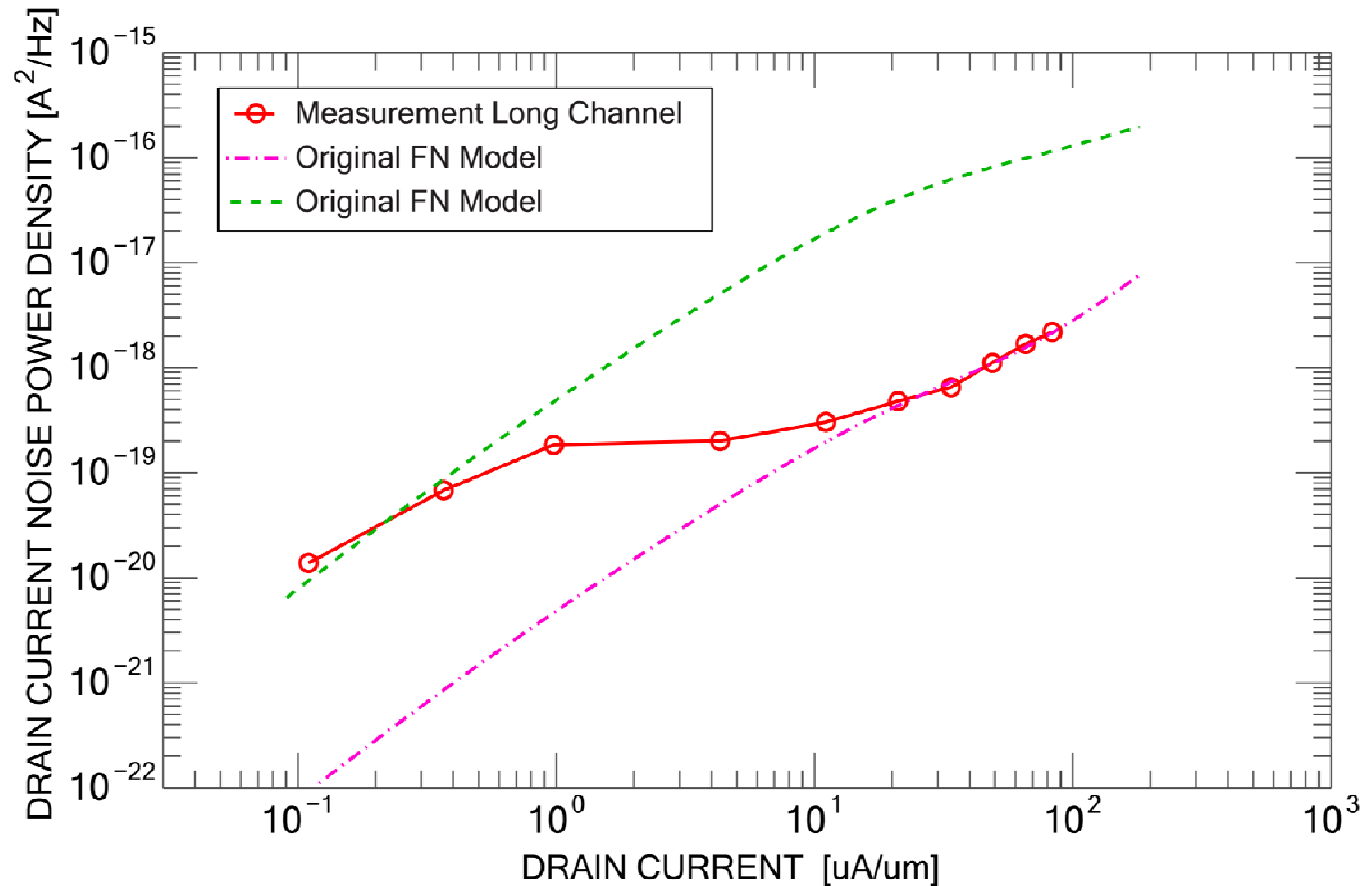
# Measurement



## Observations:

- 1) Comparable Noise in Short and long channels
- 2) Significant bias dependence

# Measurement



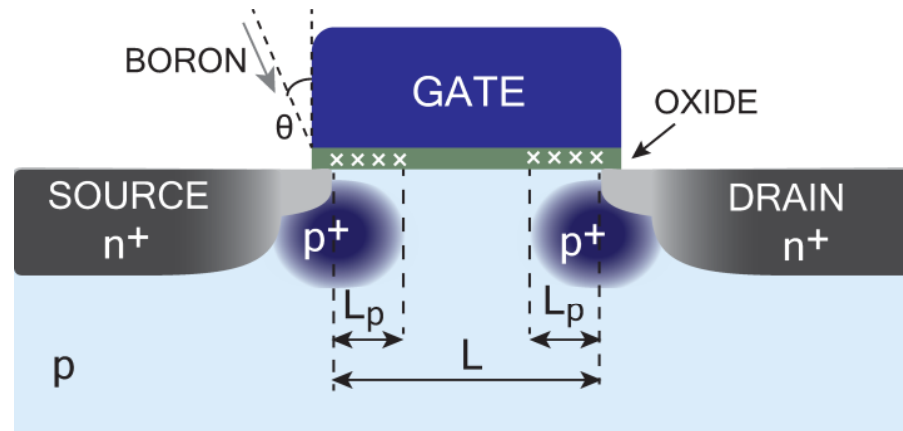
## Observations:

- 1) Comparable Noise in Short and long channels
- 2) Significant bias dependence
- 3) Usual practice of the unified flicker-noise model is inadequate

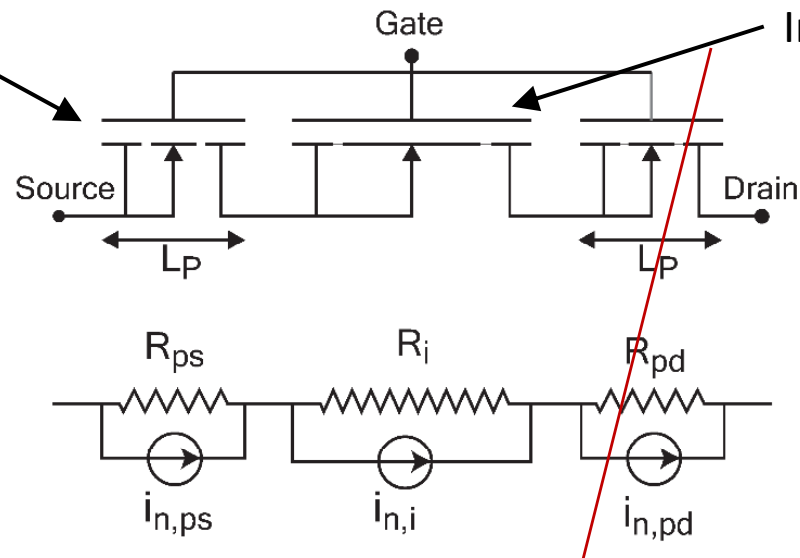


More complex mechanisms are involved.

# Methodology



Pocket MOSFET



Intrinsic MOSFET

# Methodology cont.

- Weighted contributions based on the equivalent transimpedances

$$S_{ID}(f) = \frac{R_p^2}{(R_p + R_i)^2} S_{ID,p}(f) + \frac{R_i^2}{(R_p + R_i)^2} S_{ID,i}(f)$$

The equation is enclosed in a dashed blue box. Three blue arrows point from the terms inside the box to text below: one from the first term to 'HSPICE, small signal analysis', one from the second term to 'BSIM6', and one from the denominator of the second term to 'BSIM6'.

HSPICE,  
small signal analysis

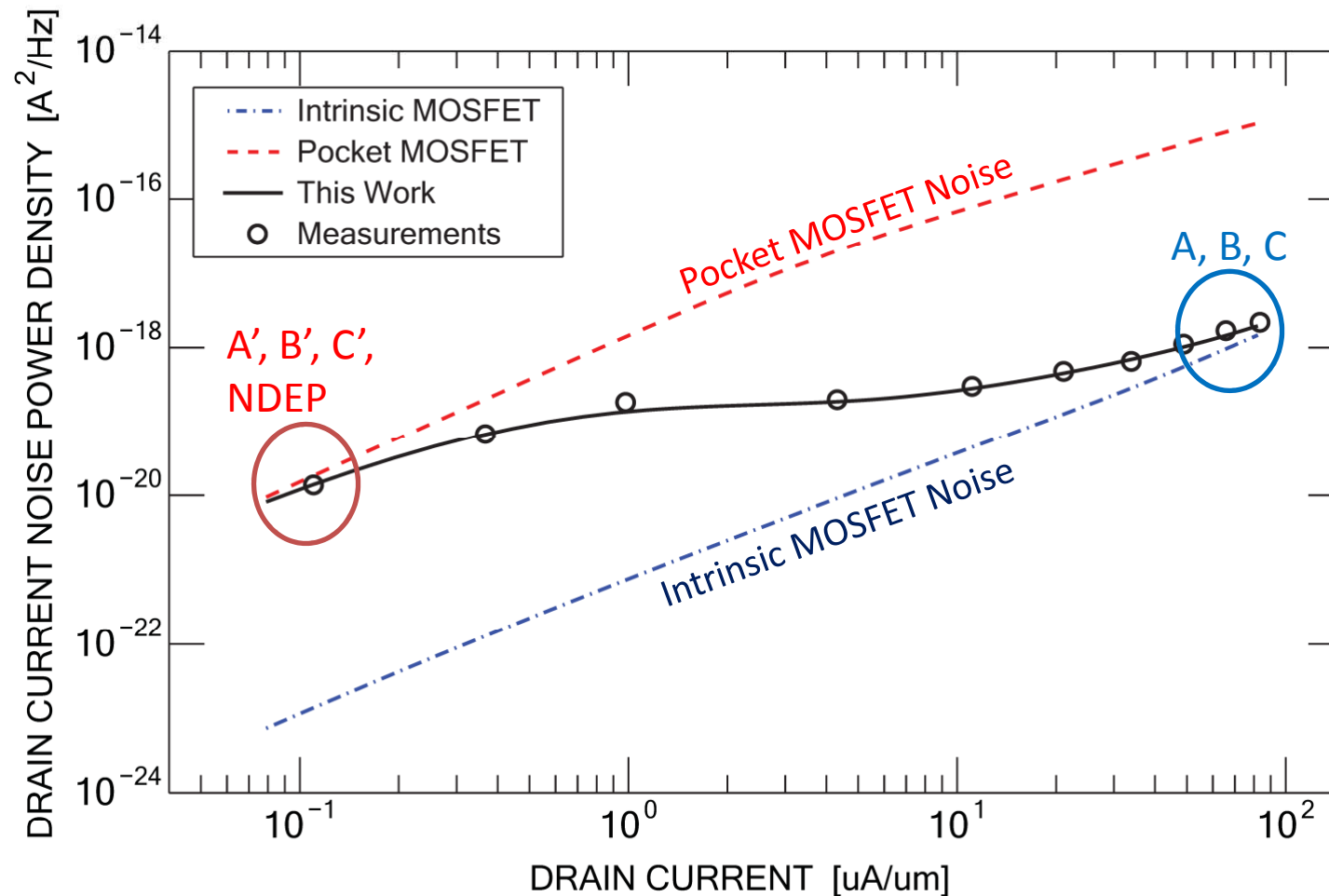
BSIM6

# BSIM6: Industry Standard bulk model

- BSIM6 – Industry standard bulk MOSFET model
  - All real device effects (SCE, CLM etc.) from BSIM4
- Symmetry
  - Currents, Caps & derivatives are symmetric @  $V_{DS}=0$
  - Provide accurate results in analog/RF simulations e.g. Harmonic Distortion simulation
- Physical Capacitance model
- Smooth behavior in all regions of operations
  - Faster Convergence



# Model Validation: Long Channel





# Discussion

$$R = \frac{1}{qn\mu} \times \frac{L}{S}$$

## Subthreshold

1. For an applied  $V_g$ , pocket MOSFET will have **smaller surface potential**
2. The carrier's number depends **exponentially** on the surface potential
3. Pocket MOSFET will show a much higher channel resistivity

4.  $R_p \gg R_i$

5. 
$$S_{ID}(f) = \frac{R_p^2}{(R_p + R_i)^2} S_{ID,p}(f) + \frac{R_i^2}{(R_p + R_i)^2} S_{ID,i}(f) \approx S_{ID,p}$$

# Discussion

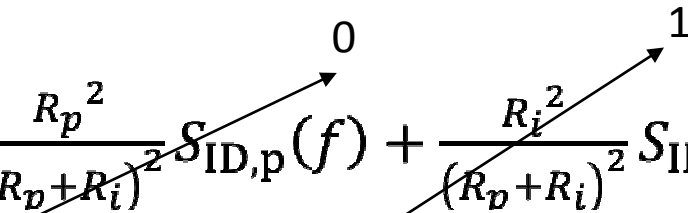
$$R = \frac{1}{qn\mu} \times \frac{L}{S}$$

## Strong Inversion

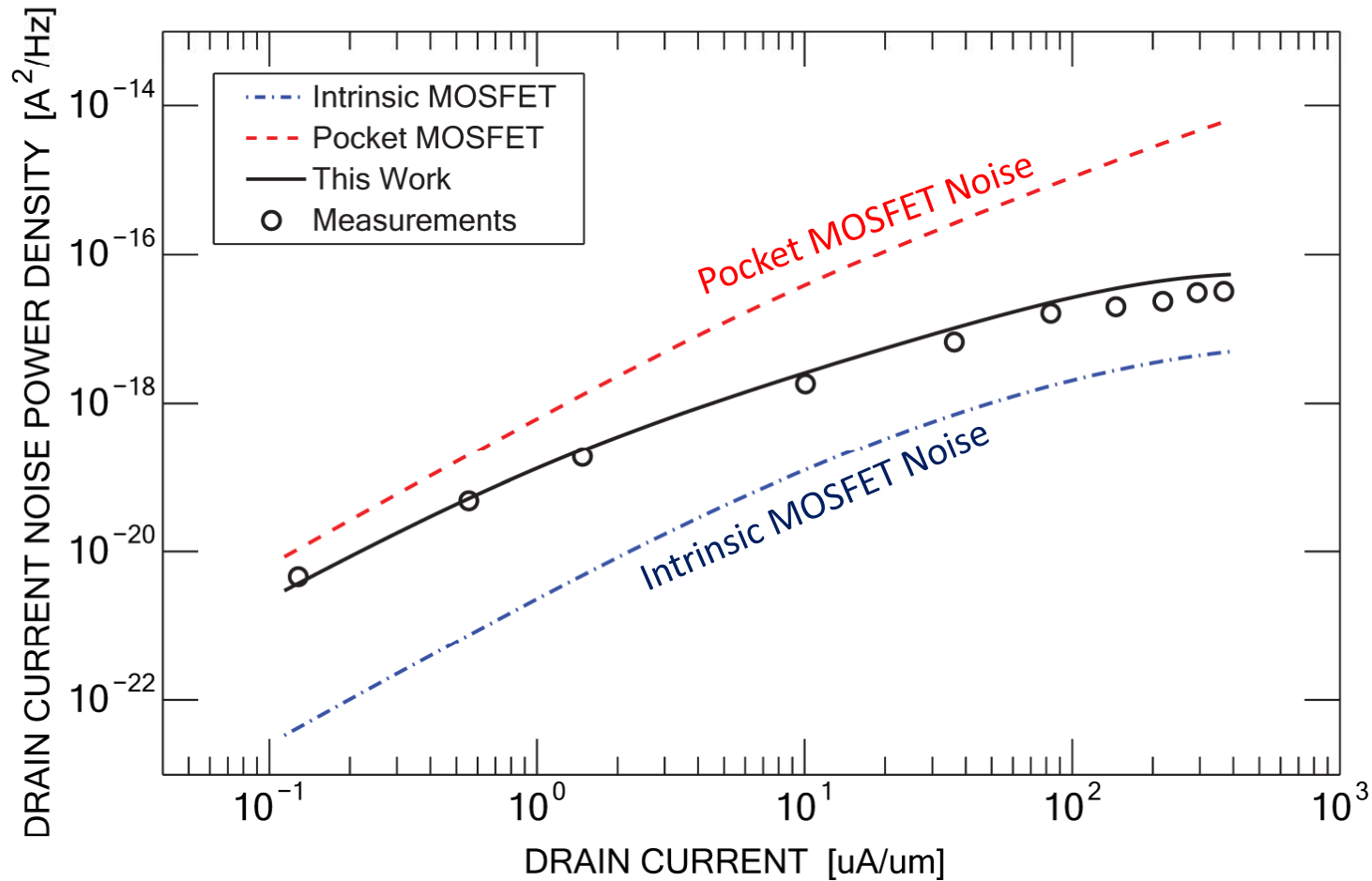
1. The resistivity of both channels drops dramatically
2. The resistance of the segments will be distinguished by their lengths

3.  $R_i \gg R_p$

4.  $S_{ID}(f) = \frac{R_p^2}{(R_p + R_i)^2} S_{ID,p}(f) + \frac{R_i^2}{(R_p + R_i)^2} S_{ID,i}(f) \approx S_{ID,i}$



# Model Validation: Short Channel



# Discussion

- **Subthreshold**

$$S_{ID} \approx S_{ID,p}$$

- **Strong Inversion**

The length of the pocket and the length of the intact channel is comparable => **a smoother and shallower transition**

$$S_{ID,i} < S_{ID} < S_{ID,p}$$

- In a case of a very short channel MOSFET, the pockets from the two sides merge => **conventional shape of the transition from subthreshold to strong inversion is restored**

# Discussion

## Unified Flicker Noise Model:

- Step 1) The noise power density of the local current fluctuations  $S_{\Delta Id}$  is calculated.

.....

- Step 2) The contributions of the local noise sources to the fluctuation of the output current are combined:

$$S_{ID}(f) = \frac{1}{L^2} \int_0^L S_{\Delta Id}(x, f) \Delta x dx$$

# Conclusions

- The usual practice of the unified flicker-noise model is **inadequate** for MOSFETs with pocket implants, BSIM4, PSP, ...
- Of particular interest for *near-threshold RF design*:  
The non-uniform bias-dependent impedance distribution causes the subthreshold FN power density to be **dominated** by the contribution from the **source-side pocket**
- The proposed model is the **only** method so far that can predict FN power density as a function of the device **geometry** and across different **bias** regimes.

**THANKS FOR LISTENING,  
ANY QUESTION?**